



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|--|
| Chip Size | 1825 |
| L | 4.57mm +1.02/-0.51mm (0.18 in +0.04/-0.02 in) |
| W | 6.35mm +0.76/-0.51mm (0.25 in +0.03/-0.02 in) |
| T | 1.27mm +1.14/-0.76mm (0.05 in +0.045/-0.03 in) |
| B | 0.51mm +0.63/-0.25mm (0.02 in +0.025/-0.01 in) |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 178mm, Plastic Tape |
| Packaging Quantity | 1100 |

General Information

| | |
|-------------------------|--|
| Series | SMD Mil PRF55681 |
| Style | SMD Chip |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov . |
| SCIP Number | de44f0ec-7e7c-4120-b42e-f63f667919b6 |
| Termination | Lead (SnPb) |
| Failure Rate | R (0.01%/1000 Hrs) |
| Testing and Reliability | MIL-PRF-55681 |
| Qualifications | MIL-PRF-55681 |
| AEC-Q200 | No |
| Miscellaneous | Termination Description: SolderCoat 60-40. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|-------------------------|------------|
| Capacitance | 0.27 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 50 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BX |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)